

**Emma Giles**Marketing & Communications Specialist - Europe  
[Emma.Giles@MacDermidAlpha.com](mailto:Emma.Giles@MacDermidAlpha.com)**PRESS RELEASE****MacDermid Alpha to Promote Latest Interconnect Technologies at the productronica Europe Exhibition**

(Waterbury, CT USA) – October, 29, 2021 – MacDermid Alpha Electronics Solutions, leaders in innovative electronic interconnect technologies, will feature their latest product and technology innovations at the upcoming productronica exhibition in Munich, Germany from Tuesday 16th – Friday 19th November.



The newly launched highly thermally conductive thermal gap filler and new bio-based conformal coating from the Electrolube brand will be one of the key highlights at the show. The recently launched [GF600 thermal gap filler](#) provides exceptional thermal performance (6.0W/m.K), and is designed to provide greater stability than traditional thermal interface materials. As a first to market, Electrolube's bio-coating contains 75% bio-organic content from renewable sources and is an eco-friendly innovation. The coating is suitable for an extremely wide range of applications including automotive and EV requirements.

The Circuitry Solutions division will highlight their complete line of final finishes, specifically the Affinity family of ENIG and ENEPIG final finishes. The newly launched connector & interconnect process M-Contact IN-200, a high-speed, high efficiency, pure indium, plating process to reduce the tendency for whisker growth, will be promoted. Also showcased will be [MacuSpec THF 100](#), the high performance copper plating technology that bridges and fills through holes in a single plating

step, as well as their complete line of leading-edge metallization processes for exceptionally reliable copper filled microvias.

The [ALPHA Argomax portfolio](#) of sintering solutions designed to address all possible design implementations for power electronics will be promoted by the Assembly Solutions division. Silver Sintering is a proven technology that overcomes many of the thermal dissipation, power cycling and high temperature stability challenges associated with power module interconnects. MacDermid Alpha's range of ALPHA Argomax sinter technology products are designed to exceed the demanding quality and reliability standards of the power semiconductor industry.

Designed to combat reliability issues in assembled chip packages, the ALPHA HiTech range of polymer materials will be also be featured at the show. [ALPHA HiTech CU21-3240](#) and [ALPHA HiTech CU31-2030](#) are one-component capillary underfills designed for the protection of assembled chip packages onto printed circuit boards, providing excellent reliability performance. [ALPHA HiTech CF31-4010](#) is a one component, high filler content, heat curable edgebond that helps strengthen the soldered assembled component, allowing it to pass reliability tests such as Drop Shock, Impact Bend and Thermal Cycle (TCT).

To learn more about MacDermid Alpha's latest innovations visit hall A4 booth 466 at productronica Europe or visit our website [MacDermidAlpha.com](http://MacDermidAlpha.com).

To register for productronica Europe please visit the productronica [website](#).

**About MacDermid Alpha Electronics Solutions:**

Through the innovation of specialty chemicals and materials under our Alpha, Compugraphics, Electrolube, Kester, and MacDermid Enthone brands, MacDermid Alpha Electronics Solutions provides solutions that power electronics interconnection. We serve all global regions and every step of device manufacturing within each segment of the electronics supply chain. The experts in our Semiconductor Solutions, Circuitry Solutions, and Assembly Solutions divisions collaborate in design, implementation, and technical service to ensure success for our partner clients. Our solutions enable our customers' manufacture of extraordinary electronic devices at high productivity and reduced cycle time.